

Title (en)

Wire sawing device

Title (de)

Drahtsägevorrichtung

Title (fr)

Dispositif de sciage par fil

Publication

EP 1437209 B1 20060816 (FR)

Application

EP 03029548 A 20031222

Priority

- CH 432003 A 20030113
- CH 12632003 A 20030718

Abstract (en)

[origin: EP1437209A1] The device has a wire strand maintained in position by a groove provided on a surface of cylindrical guides. Wires move alternately or continuously to press against a fixed saw piece (17) on a support table (18). A maintaining device (22) maintains partially or fully sawed chips (23) in parallel. The device is arranged such that widths of sawing gaps (24) are kept approximately constant during sawing of chips by wire.

IPC 8 full level

B24B 27/06 (2006.01); **B28D 5/00** (2006.01); **B28D 5/04** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP US)

B28D 5/0082 (2013.01 - EP US); **B28D 5/045** (2013.01 - EP US); **Y10T 83/7487** (2015.04 - EP US); **Y10T 83/7533** (2015.04 - EP US); **Y10T 83/754** (2015.04 - EP US); **Y10T 83/9292** (2015.04 - EP US)

Cited by

EP2711978A1; WO2013098070A1; EP2944444A1; WO2015173739A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 1437209 A1 20040714; **EP 1437209 B1 20060816**; AT E336349 T1 20060915; CH 696807 A5 20071214; DE 60307588 D1 20060928; DE 60307588 T2 20070816; ES 2269905 T3 20070401; JP 2004216549 A 20040805; JP 4510473 B2 20100721; US 2004159316 A1 20040819; US 7114424 B2 20061003

DOCDB simple family (application)

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